503674129 02/01/2016

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHENG-CHAN LI	01/20/2016
CHIH-HUI HUANG	01/20/2016
CHENG-YUAN TSAI	01/20/2016
YEUR-LUEN TU	01/20/2016

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15012288

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	18506-955	
NAME OF SUBMITTER:	ANTHONY KING	
SIGNATURE:	/Anthony King/	
DATE SIGNED:	02/01/2016	

Total Attachments: 2

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PATENT 503674129 REEL: 037635 FRAME: 0139

Your Ref.: P20150768US00

US ONLY

ASSIGNMENT

WHEREAS, I(we), <u>LI, SHENG-CHAN</u>, <u>HUANG, CHIH-HUI</u>, <u>TSAI, CHENG-YUAN</u> and <u>TU, YEUR-LUEN</u> whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled

SEMICONDUCTOR STRUCTURE AND METHOD OF MANUFACTURING THE SAME

(hereinafter referred to as the I is executed on even date herew	NVENTION) for which an application for rith unless at least one of the following i	· United States Le	tters Patent /Utility Patent
United States Design I	•		
☐ executed on:			
☐ filed on:	Serial No.:		
cstablished by PCT Int	ernational Patent Application No.:	filed:	designating the
United States of America			₩ W
☐ issued on	as U.S. Patent No.:		

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD. whose post office address is NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Assignor Name LI, SHENG-CHAN	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN (R.O.C.)
Signature of Assignor (X) LI, SHENG - CHAN	Date of Signature (X) >016. /, >0
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

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PATENT REEL: 037635 FRAME: 0140

Assignor Name HUANG, CHIH-HUI	Address NO.43, ALY. 30, LN. 165, YONG-AN RD., YONGKANG CITY, TAINAN COUNTY 710, TAIWAN (R.O.C.)
Signature of Assignor (X) HUANG, CMIH—HUI	Date of Signature (X) 20/6 / 20
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)
Assignor Name TSAI, CHENG-YUAN TSAI, Cheng - Yeran	Address NO. 101, WEN-YI ST., CHU-PEI CITY, HSIN-CHU COUNTY, TAIWAN (R.O.C.)
Signature of Assignor (X)	Date of Signature (X) 20/6. /, 20
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)
Assignor Name TU, YEUR-LUEN	Address NO. 3-6, LANE 12, GONG-XUE RD., TAICHUNG, TAIWAN (R.O.C.)
Signature of Kinggor (X)	Date of Signature (X) 20/6 / 20
Name of Wifnest (optional)	Name of Witness (optional)

Signature of Witness (Optional)

Signature of Witness (optional)